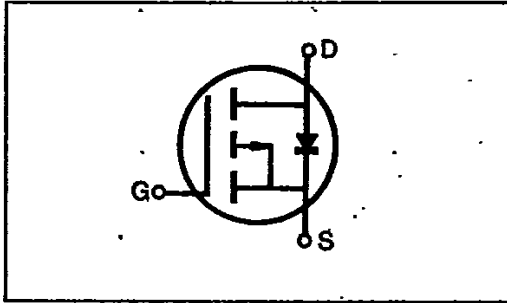


*Preliminary Specifications*

- 100 Volt, 0.2 Ohm SFET



**PRODUCT SUMMARY**

Part Number	V <sub>DS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRF/IRFP9140, IRF9540	-100V	0.2Ω	-19A
IRF/IRFP9141, IRF9541	-60V	0.2Ω	-19A
IRF/IRFP9142, IRF9542	-100V	0.3Ω	-15A
IRF/IRFP9143, IRF9543	-60V	0.3Ω	-15A

**FEATURES**

- Low R<sub>DS(on)</sub>
- Improved inductive ruggedness
- Fast switching times
- Rugged polysilicon gate cell structure
- Low input capacitance
- Extended safe operating area
- Improved high temperature reliability

**PACKAGE STYLE**

Package Type	Part Number
TO-3	IRF9140/9141/9142/9143
TO-3P	IRFP9140/9141/9142/9143
TO-220	IRF9540/9541/9542/9543

**MAXIMUM RATINGS**

Characteristic	Symbol	IRF/IRFP				Unit
		9140 9540	9141 9541	9142 9542	9143 9543	
Drain-Source Voltage (1)	V <sub>DSS</sub>	-100	-60	-100	-60	V <sub>dc</sub>
Drain-Gate Voltage (R <sub>GS</sub> =1.0MΩ) (1)	V <sub>DGR</sub>	-100	-60	-100	-60	V <sub>dc</sub>
Gate-Source Voltage	V <sub>GS</sub>	±20				V <sub>dc</sub>
Continuous Drain Current T <sub>C</sub> =25°C	I <sub>D</sub>	-19	-19	-15	-15	A <sub>dc</sub>
Continuous Drain Current T <sub>C</sub> =100°C	I <sub>D</sub>	-12	-12	-10	-10	A <sub>dc</sub>
Drain Current—Pulsed (3)	I <sub>DM</sub>	-76	-76	-60	-60	A <sub>dc</sub>
Gate Current—Pulsed	I <sub>GM</sub>	±1.5				A <sub>dc</sub>
Total Power Dissipation @ T <sub>C</sub> =25°C Derate above 25°C	P <sub>D</sub>	125 1.0				Watts W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150				°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	T <sub>L</sub>	300				°C

- Notes: (1) T<sub>J</sub>=25°C to 150°C  
 (2) Pulse test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%  
 (3) Repetitive rating: Pulse width limited by max. junction temperature

IRF9140/9141/9142/9143  
 IRFP9140/9141/9142/9143  
 IRF9540/9541/9542/9543

P-CHANNEL  
 POWER MOSFETS

T-39-23

**ELECTRICAL CHARACTERISTICS** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

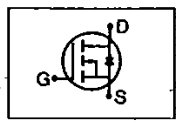
Characteristic	Symbol	Type	Min	Typ	Max	Units	Test Conditions
Drain-Source Breakdown Voltage	$BV_{DSS}$	IRF9140/2 IRFP9140/2 IRF9540/2	-100	—	—	V	$V_{GS}=0V$
		IRF9141/3 IRFP9141/2 IRF9541/3	-60	—	—	V	$I_D=-250\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	ALL	-2.0	—	-4.0	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
Gate-Source Leakage Forward	$I_{GSS}$	ALL	—	—	-100	nA	$V_{GS}=-20V$
Gate-Source Leakage Reverse	$I_{GSS}$	ALL	—	—	100	nA	$V_{GS}=20V$
Zero Gate Voltage Drain Current	$I_{DSS}$	ALL	—	—	-250	$\mu A$	$V_{DS}=\text{Max. Rating}, V_{GS}=0V$
			—	—	-1000	$\mu A$	$V_{DS}=\text{Max. Rating} \times 0.8, V_{GS}=0V, T_C=125^\circ\text{C}$
On-State Drain-Source Current(2)	$I_{D(on)}$	IRF9140/1 IRFP9140/1 IRF9540/1	-19	—	—	A	$V_{DS}>I_{D(on)} \times R_{DS(on) \text{ max.}}, V_{GS}=-10V$
		IRF9142/3 IRFP9142/3 IRF9542/3	-15	—	—	A	
Static Drain-Source On-State Resistance (2)	$R_{DS(on)}$	IRF9140/1 IRFP9140/1 IRF9540/1	—	—	0.2	$\Omega$	$V_{GS}=-10V, I_D=-10A$
		IRF9142/3 IRFP9142/3 IRF9542/3	—	—	0.3	$\Omega$	
Forward Transconductance (2)	$g_{fs}$	ALL	5.0	—	—		$V_{DS}>I_{D(on)} \times R_{DS(on) \text{ max.}}, I_D=-10A$
Input Capacitance	$C_{iss}$	ALL	—	—	1300	pF	$V_{GS}=0V, V_{DS}=-25V, f=1.0\text{MHz}$
Output Capacitance	$C_{oss}$	ALL	—	—	700	pF	
Reverse Transfer Capacitance	$C_{rss}$	ALL	—	—	400	pF	
Turn-On Delay Time	$t_{d(on)}$	ALL	—	—	30	ns	$V_{DD}=0.5BV_{DSS}, I_D=-10A, Z_0=4.7\Omega,$ (MOSFET switching times are essentially independent of operating temperature.)
Rise Time	$t_r$	ALL	—	—	15	ns	
Turn-Off Delay Time	$t_{d(off)}$	ALL	—	—	20	ns	
Fall Time	$t_f$	ALL	—	—	12	ns	
Total Gate Charge (Gate-Source Plus Gate-Drain)	$Q_g$	ALL	—	—	90	nC	$V_{GS}=-15V, I_D=-24A, V_{DS}=0.8 \text{ Max. Rating}$ (Gate charge is essentially independent of operating temperature.)
Gate-Source Charge	$Q_{gs}$	ALL	—	—	30	nC	
Gate-Drain ("Miller") Charge	$Q_{gd}$	ALL	—	—	60	nC	

**THERMAL RESISTANCE**

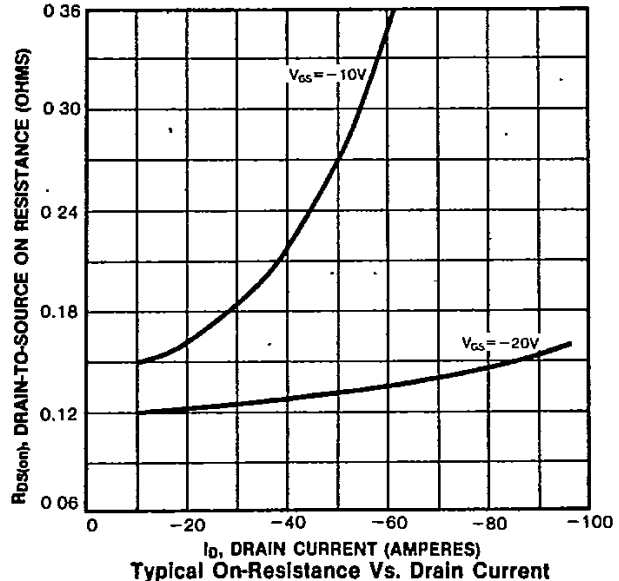
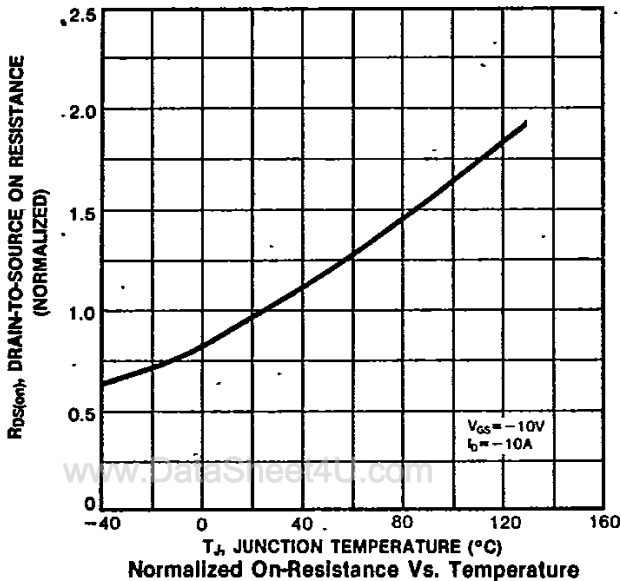
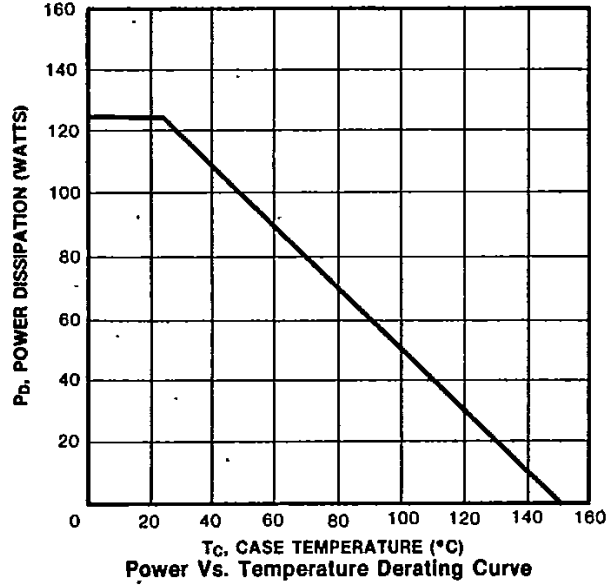
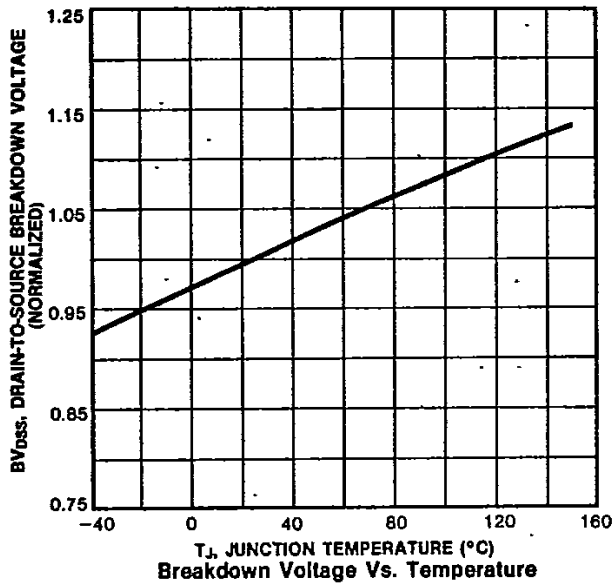
Junction-to-Case	$R_{thJC}$	ALL	—	—	1.0	K/W	
Case-to-Sink	$R_{thCS}$	ALL	—	0.1	—	K/W	Mounting surface flat, smooth, and greased
Junction-to-Ambient	$R_{thJA}$	IRFPXXXX IRF95XX	—	—	80	K/W	Free Air Operation
		IRF91XX	—	—	30	K/W	

- Notes: (1)  $T_J=25^\circ\text{C}$  to  $150^\circ\text{C}$   
 (2) Pulse test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$   
 (3) Repetitive rating: Pulse width limited by max. junction temperature

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristic	Symbol	Type	Min	Typ	Max	Units	Test Conditions
Continuous Source Current (Body Diode)	I <sub>S</sub>	IRF9140/1 IRFP9140/1 IRF9540/1	—	—	-19	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier 
		IRF9142/3 IRFP9142/3 IRF9542/3	—	—	-15	A	
Pulse Source Current (Body Diode) (3)	I <sub>SM</sub>	IRF9140/1 IRFP9140/1 IRF9540/1	—	—	-76	A	
		IRF9142/3 IRFP9142/3 IRF9542/3	—	—	-60	A	
Diode Forward Voltage (2)	V <sub>SD</sub>	IRF9140/1 IRFP9140/1 IRF9540/1	—	—	-4.2	V	T <sub>C</sub> =25°C, I <sub>S</sub> =-19A, V <sub>GS</sub> =0V
		IRF9142/3 IRFP9142/3 IRF9542/3	—	—	-4.0	V	T <sub>C</sub> =25°C, I <sub>S</sub> =-15A, V <sub>GS</sub> =0V
Reverse Recovery Time	t <sub>rr</sub>	ALL	—	—	—	ns	T <sub>J</sub> =150°C, I <sub>F</sub> =-19A, dI <sub>F</sub> /dt=100A/μs

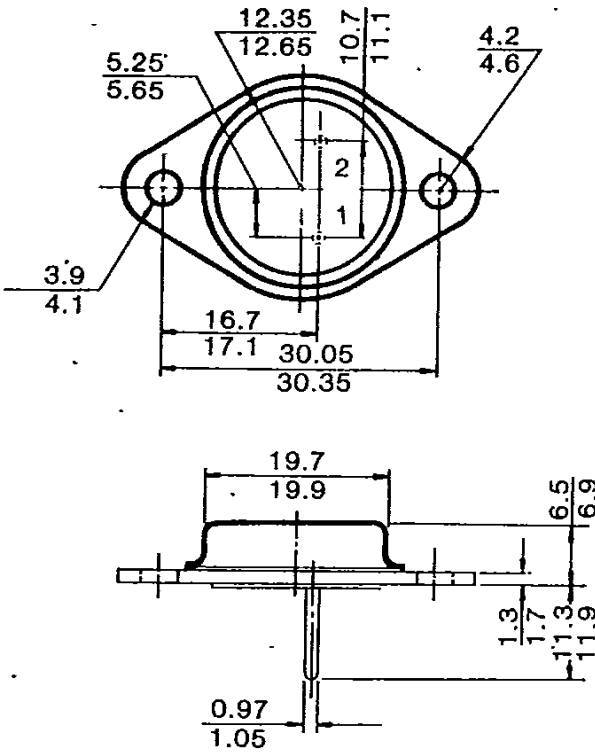
Notes: (1) T<sub>J</sub>=25°C to 150°C (2) Pulse test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%  
 (3) Repetitive rating: Pulse width limited by max. junction temperature



# PACKAGE DIMENSIONS

**TO-3(Standard Type)**

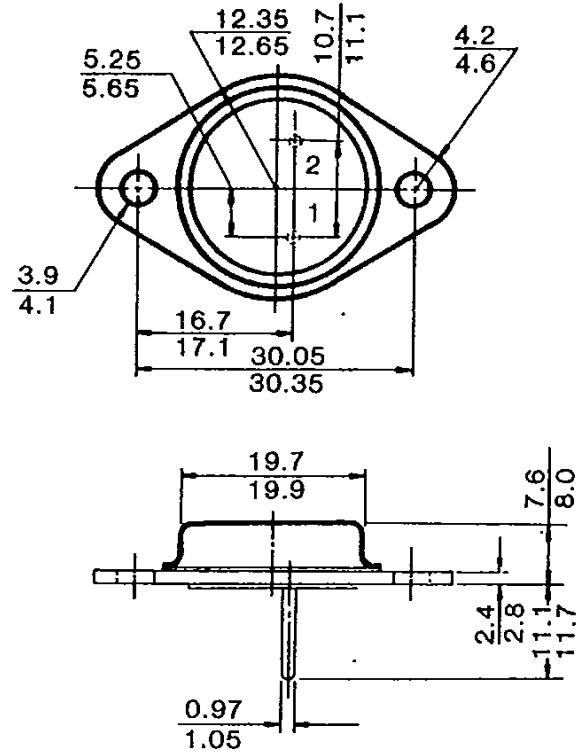
**Unit: mm**



1. Gate 2. Source Case: Drain

**TO-3(High-Voltage Type)**

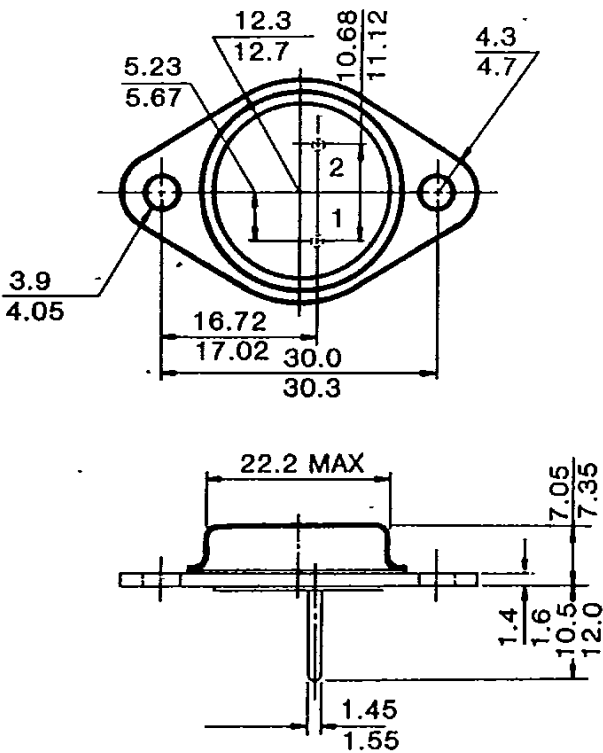
**Unit: mm**



1. Gate 2. Source Case: Drain

**TO-3(High Current Type)**

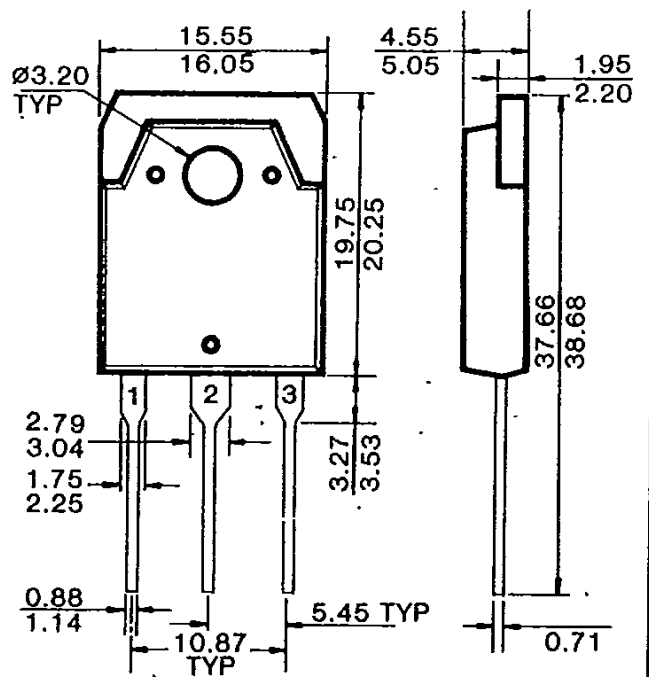
**Unit: mm**



1. Gate 2. Source Case: Drain

**TO-3P**

**Unit: mm**



1. Gate 2. Drain 3. Source

# PACKAGE DIMENSIONS

